

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1 – 44. (Canceled)

45. (New) A chip package comprising:

a semiconductor device;

a substrate having a pad having an edge not covered by a mask; and

a bump between said semiconductor device and said substrate, wherein said bump is bonded to said pad.

46. (New) The chip package of Claim 45 further comprising a post between said bump and said semiconductor device, wherein said post has a thickness of greater than 10 microns.

47. (New) The chip package of Claim 46, wherein said thickness is less than 100 microns.

48. (New) The chip package of Claim 46 further comprising a barrier layer between said post and said semiconductor device.

49. (New) The chip package of Claim 46 further comprising a metal layer between said post and said bump, wherein said metal layer has a surface on said post, said surface having a region not covered by said post.

50. (New) The chip package of Claim 49, wherein the distance between an edge of said metal layer and an edge of said post is greater than 0.2 microns.

51. (New) The chip package of Claim 45, wherein said bump comprises solder.

52. (New) The chip package of Claim 45, wherein said semiconductor device comprises a pad and a passivation layer, said post over said pad being exposed by an opening in said passivation layer, and wherein said bump is over said pad.

53. (New) The chip package of Claim 45 further comprising a barrier between said bump and said pad.

54. (New) The chip package of Claim 45, wherein said mask comprises a solder mask.